

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Michael A. Carcasi</td> <td>03/31/2010</td> </tr> <tr> <td>Benjamin M. Rathsack</td> <td>03/31/2010</td> </tr> <tr> <td>Mark H. Somervell</td> <td>03/31/2010</td> </tr> </tbody> </table>		Name	Execution Date	Michael A. Carcasi	03/31/2010	Benjamin M. Rathsack	03/31/2010	Mark H. Somervell	03/31/2010
Name	Execution Date								
Michael A. Carcasi	03/31/2010								
Benjamin M. Rathsack	03/31/2010								
Mark H. Somervell	03/31/2010								
RECEIVING PARTY DATA									
Name:	Tokyo Electron Limited								
Street Address:	3-1 Akasaka 5-chome Minato-ku								
Internal Address:	Akasaka Biz Tower								
City:	Tokyo								
State/Country:	JAPAN								
Postal Code:	107-6325								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12751362</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12751362				
Property Type	Number								
Application Number:	12751362								
CORRESPONDENCE DATA									
Fax Number:	(513)241-6234								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	513-241-2324								
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Address Line 2:	2700 Carew Tower								
Address Line 4:	Cincinnati, OHIO 45202								
ATTORNEY DOCKET NUMBER:	CT-091								
NAME OF SUBMITTER:	Debbie C. Goodman								
Total Attachments: 2									

OP \$40.00 12751362

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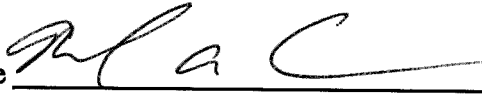
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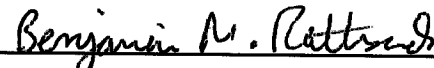
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ASSIGNMENT OF INVENTION AND PATENTS THEREON

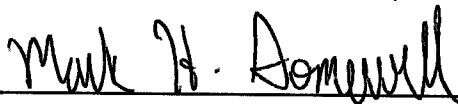
For valuable consideration, we, **Michael A. Carcasi, Benjamin M. Rathsack, Mark H. Somervell**, hereby assign to **Tokyo Electron Limited**, a Corporation of **Japan** and having a place of business at **Akasaka Biz Tower, 3-1 Akasaka 5-chome, Minato-ku, Tokyo 107-6325 Japan**, and its successors and assigns (collectively hereinafter called "the Assignee"), our entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent filed herewith, entitled **METHOD OF SLIMMING RADIATION-SENSITIVE MATERIAL LINES IN LITHOGRAPHIC APPLICATIONS** and filed on **March 31, 2010** as Patent Application No. **12/751,362** preparatory to obtaining Letter Patent of the U.S. thereof, this assignment including said application, any continuation, division or continuation-in-part thereof and/or substitute therefor, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, and design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment. **We hereby authorize and request any one of the attorneys of Wood, Herron & Evans L.L.P., 2700 Carew Tower, 441 Vine Street, Cincinnati, OH 45202, to insert herein the filing date and application serial number of said application when known.**

Inventor's Signature  Date 3/31/2010

Full Name: Michael A. Carcasi
Residence: Austin, Texas

Inventor's Signature  Date 3/31/2010

Full Name: Benjamin M. Rathsack
Residence: Austin, Texas

Inventor's Signature  Date 3/31/2010

Full Name: Mark H. Somervell
Residence: Austin, Texas